

# BLF7G10L-250; BLF7G10LS-250

Power LDMOS transistor

Rev. 5 — 1 September 2015

AMPLEON

Product data sheet

## 1. Product profile

### 1.1 General description

250 W LDMOS power transistor for base station applications at frequencies from 869 MHz to 960 MHz.

**Table 1. Typical performance**

Test signal: 3GPP; test model 1; 64 DPCH; PAR = 7.5 dB at 0.01 % probability on CCDF per carrier; carrier spacing = 5 MHz. Typical RF performance at  $T_{case} = 25\text{ }^{\circ}\text{C}$ .

Test signal	f (MHz)	$I_{Dq}$ (mA)	$V_{DS}$ (V)	$P_{L(AV)}$ (W)	$G_p$ (dB)	$\eta_D$ (%)	ACPR (dBc)
2-carrier W-CDMA	869 to 894 <a href="#">[1]</a>	1800	30	60	19.5	27.4	-35.6
2-carrier W-CDMA	920 to 960 <a href="#">[2]</a>	1800	30	60	19.5	30.5	-34

[1] In a common source class-AB application test circuit.

[2] In a common source class-AB production test circuit.

### 1.2 Features and benefits

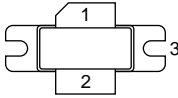
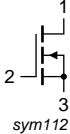
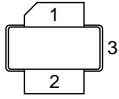
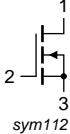
- Excellent ruggedness
- High efficiency
- Low  $R_{th}$  providing excellent thermal stability
- Designed for broadband operation (869 MHz to 960 MHz)
- Lower output capacitance for improved performance in Doherty applications
- Designed for low memory effects providing excellent pre-distortability
- Internally matched for ease of use (input and output)
- Integrated ESD protection
- Compliant to Directive 2002/95/EC, regarding Restriction of Hazardous Substances (RoHS)

### 1.3 Applications

- RF power amplifiers for W-CDMA base stations and multi carrier applications in the 869 MHz to 960 MHz frequency range

## 2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
<b>BLF7G10L-250 (SOT502A)</b>			
1	drain		 sym112
2	gate		
3	source		
<b>BLF7G10LS-250 (SOT502B)</b>			
1	drain		 sym112
2	gate		
3	source		

[1] Connected to flange

## 3. Ordering information

Table 3. Ordering information

Type number	Package		Version
	Name	Description	
BLF7G10L-250	-	flanged ceramic package; 2 mounting holes; 2 leads	SOT502A
BLF7G10LS-250	-	earless flanged ceramic package; 2 leads	SOT502B

## 4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DS}$	drain-source voltage		-	65	V
$V_{GS}$	gate-source voltage		-0.5	+13	V
$T_{stg}$	storage temperature		-65	+150	°C
$T_j$	junction temperature		-	200	°C

## 5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-c)}$	thermal resistance from junction to case	$T_{case} = 80\text{ °C}$ ; $P_L = 60\text{ W (CW)}$ ; $V_{DS} = 30\text{ V}$ ; $I_{Dq} = 1800\text{ mA}$	0.38	K/W

## 6. Characteristics

**Table 6. DC characteristics**

$T_j = 25\text{ }^\circ\text{C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{(BR)DSS}$	drain-source breakdown voltage	$V_{GS} = 0\text{ V}; I_D = 3.3\text{ mA}$	65	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$V_{DS} = 10\text{ V}; I_D = 330\text{ mA}$	1.50	1.9	2.30	V
$I_{DSS}$	drain leakage current	$V_{GS} = 0\text{ V}; V_{DS} = 28\text{ V}$	-	-	5	$\mu\text{A}$
$I_{DSX}$	drain cut-off current	$V_{GS} = V_{GS(th)} + 3.75\text{ V}; V_{DS} = 10\text{ V}$	-	56	-	A
$I_{GSS}$	gate leakage current	$V_{GS} = 11\text{ V}; V_{DS} = 0\text{ V}$	-	-	0.5	mA
$g_{fs}$	forward transconductance	$V_{DS} = 10\text{ V}; I_D = 11.55\text{ A}$	-	22	-	S
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = V_{GS(th)} + 3.75\text{ V}; I_D = 11.55\text{ A}$	-	57	-	$\text{m}\Omega$

**Table 7. RF characteristics**

Test signal: 2-carrier W-CDMA; PAR = 7.5 dB at 0.01 % probability on the CCDF; 3GPP test model 1; 64 DPCH;  $f_1 = 920\text{ MHz}; f_2 = 925\text{ MHz}; f_3 = 955\text{ MHz}; f_4 = 960\text{ MHz}$ ; RF performance at  $V_{DS} = 30\text{ V}; I_{Dq} = 1800\text{ mA}; T_{case} = 25\text{ }^\circ\text{C}$ ; unless otherwise specified; in a class-AB production test circuit.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$G_p$	power gain	$P_{L(AV)} = 60\text{ W}$	18.5	19.5	-	dB
$RL_{in}$	input return loss	$P_{L(AV)} = 60\text{ W}$	-	-15.5	-10	dB
$\eta_D$	drain efficiency	$P_{L(AV)} = 60\text{ W}$	27	30.5	-	%
ACPR	adjacent channel power ratio	$P_{L(AV)} = 60\text{ W}$	-	-34	-31	dBc

## 7. Test information

### 7.1 Ruggedness in class-AB operation

The BLF7G10L-250 and BLF7G10LS-250 are capable of withstanding a load mismatch corresponding to VSWR = 10 : 1 through all phases under the following conditions:  $V_{DS} = 30\text{ V}; I_{Dq} = 1800\text{ mA}; P_L = 200\text{ W (CW)}; f = 920\text{ MHz to }960\text{ MHz}$ .

### 7.2 Impedance information

**Table 8. Typical impedance information**

$I_{Dq} = 1800\text{ mA};$  main transistor  $V_{DS} = 30\text{ V}.$   
 $Z_S$  and  $Z_L$  defined in [Figure 1](#).

f (MHz)	$Z_S$ ( $\Omega$ )	$Z_L$ ( $\Omega$ )
925	3.1 - j3.3	1.0 - j1.7
942	3.2 - j3.3	1.0 - j1.6
960	3.4 - j3.5	0.9 - j1.4

